


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	MDG/23/14099
1.3 Title of PCN	Implementation of a PBO (Polybenzoxazole) protective layer over product passivation for STM8A (AUTOMOTIVE) listed products
1.4 Product Category	STM8A
1.5 Issue date	2023-06-22

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRAUSE INA
2.1.2 Phone	+49 89460062370
2.1.3 Email	ina.krause@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Wafer Fab (Process)	Change of top layer on die	ST Singapore

4. Description of change

	Old	New
4.1 Description	The wafer passivation layer has no protective layer.	Implementation of a PBO (Polybenzoxazole) protective layer on top of the wafer passivation layer is proposed to customer.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Reliability will be improved - PBO is a stress relief coating used as a protective layer for passivation layer.	

5. Reason / motivation for change

5.1 Motivation	Part of the strategy is to eradicate passivation damage on dice. A protective layer (PBO) on top of product passivation to be implemented to further reduce the baseline defectiveness level, and to protect versus possible quality excursions.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST internal tools
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7. Timing / schedule

7.1 Date of qualification results	2023-09-07
7.2 Intended start of delivery	2023-09-07
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	14099 MDG-MCD_PBO_Implementation_Plan and context.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-06-22

9. Attachments (additional documentations)

14099 Public product.pdf
14099 MDG-MCD_PBO_Implementation_Plan and context.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM8AF6266TCX	
2851064	STM8AF6246ITCY	

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